Day : Wednesday
Date: 1/23/2002
Time: 15:50:46

PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = ECHIGO
First Name = FUMIO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
07334523	Not Issued	166	04/07/1989	MAGNETIC RECORDING MEDIUM	ECHIGO , FUMIO
07690489	5342668	150	04/24/1991	MAGNETIC RECORDING MEDIUM HAVING IMPROVED ELECTROMAGNETIC CONVERSION CHARACTERISTICS AND DURABILITY	ECHIGO , FUMIO
07846686	Not Issued	161	03/04/1992	DISK-SHAPED MAGNETIC RECORDING MEDIUM	ECHIGO , FUMIO
07892701	Not Issued	166	05/29/1992	MAGNETIC RECORDING MEDIUM	ECHIGO , FUMIO
08038194	5399407	150	03/26/1993	MAGNETIC RECORDING MEDIUM	ECHIGO , FUMIO
09110794	6037037	150	07/06/1998	MAGNETIC RECORDING MEDIUM	ECHIGO , FUMIO
09506318	Not Issued	030	02/17/2000	NON-WOVEN FABRIC MATERIAL AND PREPREG, AND CIRCUIT BOARD	ECHIGO, FUMIO

				USING THE SAME	
09573826	Not Issued	020	05/18/2000	MASK FILM, ITS MANUFACTURING METHOD, AND MANUFACTURING METHOD OF CIRCUIT BOARD USING THE SAME	ECHIGO, FUMIO
09734593	Not Issued	030	12/13/2000	REMOVABLE FILM, A SUBSTRATE WITH FILM, A PROCESS FOR FORMING THE REMOVABLE FILM AND A PROCESS FOR THE MANUFACTURING OF THE CIRCUIT BOARD	ECHIGO, FUMIO
09879385	Not Issued	030	06/12/2001	PRINTED CIRCUIT BOARD AND METHOD OF MANUFACTURING THE SAME	ECHIGO, FUMIO
09919319	Not Issued	030	07/31/2001	PRINTED CIRCUIT BOARD AND METHOD FOR PRODUCING THE SAME	ECHIGO, FUMIO
09928869	Not Issued	030	08/13/2001	CIRCUIT BOARD AND PRODUCTION OF THE SAME	ECHIGO, FUMIO
09956205	Not Issued	030	09/18/2001	CIRCUIT BOARD ELECTRICALLY INSULATING MATERIAL, CIRCUIT BOARD AND METHOD FOR MANUFACTURING THE SAME	ECHIGO, FUMIO
09962245	Not Issued	030	09/26/2001	RESIN BOARD, MANUFACTURING PROCESS FOR RESIN BOARD, CONNECTION MEDIUM BODY,	ECHIGO, FUMIO

				CIRCUIT BOARD AND MANUFACTURING PROCESS FOR CIRCUIT BOARD	
09986453	Not Issued	019	11/08/2001	CIRCUIT BOARD AND ITS MANUFACTURE METHOD	ECHIGO, FUMIO

Inventor Search Completed: Search Completed: No Records to Display.

Search Another: Inventor

Last Name ECHIGO

First Name FUMIO

Search

(To go back use Back button on your browser toolbar.)

Back to PALM | ASSIGNMENT | OASIS | Home page

Day : Wednesday
Date: 1/23/2002
Time: 15:51:43

PALM INTRANET

Inventor Name Search Result

Your Search was:

Last Name = KAWAKITA
First Name = YOSHIHIRO

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08959154	6205657	150	10/28/1997	PRINTED CIRCUIT BOARD AND METHOD FOR PRODUCING THE SAME	KAWAKITA , YOSHIHIRO
09081815	6015872	150	05/20/1998	SUBSTRATE FOR PRINTED CIRCUIT BOARD	KAWAKITA , YOSHIHIRO
09159376	6174589	150	09/23/1998	PRINTED CIRCUIT BOARD AND METHOD FOR PRODUCING THE SAME	KAWAKITA , YOSHIHIRO
09506318	Not Issued	030	02/17/2000	NON-WOVEN FABRIC MATERIAL AND PREPREG, AND CIRCUIT BOARD USING THE SAME	KAWAKITA, YOSHIHIRO
09956205	Not Issued	030	09/18/2001	CIRCUIT BOARD ELECTRICALLY INSULATING MATERIAL, CIRCUIT BOARD AND METHOD FOR MANUFACTURING THE SAME	KAWAKITA, YOSHIHIRO
09962245	Not Issued	030	09/26/2001	RESIN BOARD, MANUFACTURING	KAWAKITA, YOSHIHIRO

				PROCESS FOR RESIN BOARD, CONNECTION MEDIUM BODY, CIRCUIT BOARD AND MANUFACTURING PROCESS FOR CIRCUIT BOARD	
09986453	Not Issued	019	11/08/2001	CIRCUIT BOARD AND ITS MANUFACTURE METHOD	KAWAKITA, YOSHIHIRO
09998327	Not Issued	020	12/03/2001	CIRCUIT SUBSTRATE AND MANUFACTURING METHOD THEREOF	KAWAKITA, YOSHIHIRO

Inventor Search Completed: Search Completed: No Records to Display.

Search Another: Inventor

Last Name KAWAKITA

First Name YOSHIHIRO

Search

(To go back use Back button on your browser toolbar.)

Back to PALM | ASSIGNMENT | OASIS | Home page

WEST

Generate Collection

Search Results - Record(s) 1 through 3 of 3 returned.

☐ 1. Document ID: US 6015872 A Relevance Rank: 52

L1: Entry 3 of 3 File: USPT Jan 18, 2000

US-PAT-NO: 6015872
DOCUMENT-IDENTIFIER: US 6015872 A

TITLE: Substrate for printed circuit board

DATE-ISSUED: January 18, 2000

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kawakita; Yoshihiro	Neyagawa			JPX
Hasegawa; Masanaru	Yawata			JPX
Sakamoto; Kazunori	Katano			JPX
Hatanaka; Hideo	Katano			JPX

US-CL-CURRENT: 528/102; 428/901

ABSTRACT:

To address the problem of difficulty of making compatible flame retarding property and electrical and mechanical characteristics in conventional printed interconnection substrates, the present invention employs, in a substrate for printed circuit board of which the insulating material comprises a thermosetting resin composition comprising an epoxy resin main component and a curing agent, an epoxy resin containing a brominated phenol novolac type epoxy resin having a biphenyl skeleton as the main component or a curing agent containing a brominated phenol novolac type curing resin. It provides a substrate for printed circuit board which has an extremely high flame retarding property and a superior heat resistance and humidity resistance, as well as a high insulating reliability and a superior high frequency characteristic.

9 Claims, 0 Drawing figures Exemplary Claim Number: 1

Full | Title | Citation | Front | Review | Classification | Date | Reference | Claims | KWIC | Draw Desc | Image

☐ 2. Document ID: US 6174589 B1 Relevance Rank: 52

L1: Entry 2 of 3 File: USPT Jan 16, 2001

US-PAT-NO: 6174589
DOCUMENT-IDENTIFIER: US 6174589 B1

TITLE: Printed circuit board and method for producing the same

DATE-ISSUED: January 16, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kawakita; Yoshihiro	Osaka			JPX
Nakatani; Seiichi	Osaka			JPX
Tanahashi; Masakazu	Osaka			JPX

US-CL-CURRENT: 428/209; 174/258, 428/901

ABSTRACT:

A printed circuit board includes insulating layers formed by impregnating a base material with a resin and a metal foil pattern formed on a desired layer of the insulating layers. Ions for forming a hardly soluble metal salt by combining with metal ions free from a portion of the board or a sulfur-containing compound for reacting with the metal ion are present in the insulating layer or on a surface of the metal foil pattern. Furthermore, a method for producing the printed circuit board includes any one of the steps of adding the ions or the sulfur-containing compound to the resin varnish, impregnating a base material with the solution of the ions or the sulfur-containing compound, or applying the solution onto the surface of the metal foil pattern, in order to allow the ions or the sulfur-containing compound to exist in the printed circuit board.

13 Claims, 0 Drawing figures Exemplary Claim Number: 1

☐ 3. Document ID: US 6205657 B1 Relevance Rank: 52

L1: Entry 1 of 3 File: USPT Mar 27, 2001

US-PAT-NO: 6205657
DOCUMENT-IDENTIFIER: US 6205657 B1

TITLE: Printed circuit board and method for producing the same

DATE-ISSUED: March 27, 2001

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kawakita; Yoshihiro	Osaka			JPX
Nakatani; Seiichi	Osaka			JPX
Tanahashi; Masakazu	Osaka			JPX

US-CL-CURRENT: 29/846; 427/409, 427/418, 428/195

ABSTRACT:

A printed circuit board includes insulating layers formed by impregnating a base material with a resin and a metal foil pattern formed on a desired layer of the insulating layers. Ions for forming a hardly soluble metal salt by combining with metal ions free from a portion of the board or a sulfur-containing compound for reacting with the metal ion are present in the insulating layer or on a surface of the metal foil pattern. Furthermore, a method for producing the printed circuit board includes any one of the steps of adding the ions or the sulfur-containing compound to the resin varnish, impregnating a base material with the solution of the ions or the sulfur-containing compound, or applying the solution onto the surface of the metal foil pattern, in order to allow the ions or the sulfur-containing compound to exist in the printed circuit board.

33 Claims, 0 Drawing figures Exemplary Claim Number: 1

09/506318

STN search

```
=> s non-woven or unwoven
L1         3487 NON-WOVEN OR UNWOVEN

=> s fabric? or textile?
L2       734698 FABRIC? OR TEXTILE?

=> s ( synthetic fiber?) or (synthetic fibre?)
L3        74587 (SYNTHETIC FIBER?) OR (SYNTHETIC FIBRE?)

=> s binder? (l) glass
L4        15935 BINDER? (L) GLASS

=> set msteps on
SET COMMAND COMPLETED

=> s l1 (l) l2 (l) l3
L5            0 FILE TEXTILETECH
L6            7 FILE WTEXTILES
L7            1 FILE PIRA
L8           53 FILE CAPLUS

TOTAL FOR ALL FILES
L9           61 L1 (L) L2 (L) L3

=> s l9 and l4
L10           0 FILE TEXTILETECH
L11           0 FILE WTEXTILES
L12           0 FILE PIRA
L13           1 FILE CAPLUS

TOTAL FOR ALL FILES
L14           1 L9 AND L4

=> d bib,abs

L14  ANSWER 1 OF 1  CAPLUS  COPYRIGHT 2002 ACS
AN   1995:673985  CAPLUS
DN   123:58215
TI   Laminate and molded products from same
IN   Aoyama, Kunitoshi; Myazaki, Masaichi
PA   Ngk Insulators Ltd, Japan; Nikko Kk
SO   Jpn. Kokai Tokkyo Koho, 6 pp.
     CODEN: JKXXAF
DT   Patent
LA   Japanese
FAN.CNT 1
     PATENT NO.        KIND  DATE          APPLICATION NO.   DATE
     ---------------   ----  --------      ---------------   --------
PI   JP 07068688        A2   19950314      JP 1993-221895    19930907
AB   The title laminate is obtained by laminating a layer based on a compn.
     contg. wood pulp, natural or synthetic fiber, and
     binder with a layer based on a compn. contg. glass
     fiber, synthetic fiber, unwoven
     fabric, and binder. The side with the latter layer is
     further laminated with a layer based on a compn. contg. wood pulp, natural
     or synthetic fiber, and binder. The above
     laminates are heat and pressure molded in a die to produce products having
     the desired shape.


=> s l1 and l2 and l3
L15           3 FILE TEXTILETECH
L16          12 FILE WTEXTILES
```

L17 14 FILE PIRA
L18 150 FILE CAPLUS

TOTAL FOR ALL FILES
L19 179 L1 AND L2 AND L3

=> l19 and l4
L19 IS NOT A RECOGNIZED COMMAND
The previous command name entered was not recognized by the system.
For a list of commands available to you in the current file, enter
"HELP COMMANDS" at an arrow prompt (=>).

=> s l19 and l4
L20 1 FILE TEXTILETECH
L21 1 FILE WTEXTILES
L22 0 FILE PIRA
L23 4 FILE CAPLUS

TOTAL FOR ALL FILES
L24 6 L19 AND L4

=> d l20 bib,abs

L20 ANSWER 1 OF 1 TEXTILETECH COPYRIGHT 2002 Inst. of Textile Technology
AN 432305 TEXTILETECH
DN 198210394
TI INNOVATIONS IN **NON-WOVEN FABRICS**.
SO Vetir, No. 11: 14 (Nov. 1981).
CODEN: VETIB7
DT Journal
LA French
AB Several nonwoven **fabrics** manufacturers belonging to the EDANA (European Association of Nonwoven **Fabric** Producers) in Brussels have developed some new **fabrics** serving a variety of purposes: Holnest (100% thermosoldered polypropylene, 50% hydrophilic fibers, 50% hydrophobic fibers -- hygiene), Paradur (**synthetic fibers** saturated with latex **binders** -- industry: shoes to automobiles), Solaris (metallic polyester film sealed with vinyl on a base of nonwoven mineral fibers and **glass** -- paper substitute), and Gifyl (several layers of heat treated fibrillated and bicomponent polypropylene fibers -- industrial protection masks).

=> d l21 bib,abs

L21 ANSWER 1 OF 1 WORLD TEXTILES COPYRIGHT 2002 Elsevier Science B.V.
AN 1999:1981933 WTEXTILES
TI **Non-woven** fiber mat and method for forming same
IN Owens Corning Fiberglas Technology, Inc.; Helwig G.S.; Miller W.S.; Householder, K.A.
SO Official Gazette of the U.S. Patent and Trademark Office - Patents, (1999), 1225/2
ISSN: 0098-1133
PI US 5935879
DT Journal; Patent
CY United States
LA English
AV EMDOCS
AB The present invention is a **non-woven** fiber mat suitable for reinforcing resilient sheet floor coverings, such as vinyl floor coverings. The **non-woven** fiber mat is in the form of a sheet of reinforcement fibers which at least includes semi-coiled fibers and can also include coiled fiber, with one or more

turns, and even some relatively straight or slightly curved fibers. It is desirable for most, if not all, of the reinforcement fibers to be made from **glass**. However, it may also be desirable for the reinforcement fibers to include **glass** fibers and **synthetic fibers**. It may even be possible for the reinforcement fibers to include only non-**glass** fibers. At least one polymeric **binder** is used for bonding together the reinforcement fibers so as to make the fiber mat a suitable substrate for reinforcing resilient sheet floor coverings, such as an interlayer for vinyl floor coverings. By using a **non- woven** fiber mat containing reinforcement fibers that are not completely straight and capable of interlocking with one another, a resilient sheet floor covering made with such a mat can exhibit improved planar compressibility. IPC B32B.

=> d his

(FILE 'HOME' ENTERED AT 14:55:48 ON 27 FEB 2002)

FILE 'STNGUIDE' ENTERED AT 14:56:20 ON 27 FEB 2002

FILE 'TEXTILETECH, WTEXTILES, PIRA, CAPLUS' ENTERED AT 15:07:15 ON 27 FEB 2002

```
L1          3487 S NON-WOVEN OR UNWOVEN
L2        734698 S FABRIC? OR TEXTILE?
L3         74587 S ( SYNTHETIC FIBER?) OR (SYNTHETIC FIBRE?)
L4         15935 S BINDER? (L) GLASS
                 SET MSTEPS ON
L5             0 FILE TEXTILETECH
L6             7 FILE WTEXTILES
L7             1 FILE PIRA
L8            53 FILE CAPLUS
     TOTAL FOR ALL FILES
L9            61 S L1 (L) L2 (L) L3
L10            0 FILE TEXTILETECH
L11            0 FILE WTEXTILES
L12            0 FILE PIRA
L13            1 FILE CAPLUS
     TOTAL FOR ALL FILES
L14            1 S L9 AND L4
L15            3 FILE TEXTILETECH
L16           12 FILE WTEXTILES
L17           14 FILE PIRA
L18          150 FILE CAPLUS
     TOTAL FOR ALL FILES
L19          179 S L1 AND L2 AND L3
L20            1 FILE TEXTILETECH
L21            1 FILE WTEXTILES
L22            0 FILE PIRA
L23            4 FILE CAPLUS
     TOTAL FOR ALL FILES
L24            6 S L19 AND L4
```

=> d l23 1-4 bib,abs

L23 ANSWER 1 OF 4 CAPLUS COPYRIGHT 2002 ACS
AN 2001:710327 CAPLUS
DN 135:265839
TI Electromagnetic wave absorption sheet.
IN Matsumura, Kazuhito; Yoshida, Kenichi; Iwai, Toru; Nakata, Shuichi; Yoshisawa, Kiyoto
PA Foundation for Scientific Technology Promotion, Japan; Sumitomo Electric

Industries, Ltd.; Kanto Kosen K. K.
SO Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 2001267783	A2	20010928	JP 2000-72205	20000315

AB A low-cost electromagnetic wave absorption sheet comprises an **non-woven** cloth from metal fibers, which are formed by cutting a metal wire and have undefined cross sectional faces, **binder** fibers or its blend with non-**binder** fibers, a metal cladding on the one side of the cloth from an electromagnetic wave reflection metal of Fe, Al, Cu, or their alloys, and an optional space-retaining filling material. Specifically, the metal fibers may comprise a ferrite stainless steel, Fe, or Cu, and the non-**binder** fibers may comprise **glass** fibers or alumina/silica ceramic fibers.

L23 ANSWER 2 OF 4 CAPLUS COPYRIGHT 2002 ACS
AN 2001:101386 CAPLUS
DN 134:164433
TI Hydrodynamically bonded carrier webs, their production and their use
IN Plotz, Kurt
PA Johns Manville International, Inc., USA
SO PCT Int. Appl., 16 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 4

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI WO 2001009421	A2	20010208	WO 2000-IB1783	20000726
W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CR, CU, CZ, DE, DK, DM, DZ, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, TZ, UA, UG, UZ, VN, YU, ZA, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM				
RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZW, AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG				
DE 19935408	A1	20010208	DE 1999-19935408	19990730
DE 19952432	A1	20010621	DE 1999-19952432	19991030
DE 19955713	C1	20010705	DE 1999-19955713	19991118
AU 2001014090	A5	20010219	AU 2001-14090	20000726

PRAI DE 1999-19935408 A 19990730
DE 1999-19935531 A 19990730
DE 1999-19950957 A 19991016
DE 1999-19952432 A 19991030
DE 1999-19955713 A 19991118
DE 1999-19955730 A 19991118
WO 2000-IB1783 W 20000726

AB The prodn. of bonded nonwovens carriers includes providing a **glass** staple fiber contg. nonwoven which is pre-consolidated with a **binder**. The **glass** staple fiber **non-woven** is placed adjacent to one or more nonwovens of **synthetic fibers** and hydrodynamically needled at a water beam pressure in the range of 100-400 bar. The nonwovens are suitable for floor and wall coverings with good mech. stability and may be bituminized for use as roofing felts.

L23 ANSWER 3 OF 4 CAPLUS COPYRIGHT 2002 ACS

AN 1999:522601 CAPLUS
Correction of: 1999:236906
DN 131:131230
Correction of: 130:313159
TI Hydrophilic **non woven** construction sheets from long thermoplastic fibers and hydrophilic polymer binders for sand-holding sheets for dikes or wharfs with improved sinking properties in water
IN Ito, Tessai; Yakage, Yoshikazu; Horiguchi, Taigi
PA Toray Industries, Inc., Japan
SO Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11100821	A2	19990413	JP 1997-263616	19970929

AB The hydrophilic nonwoven **fabrics** with high tensile strength comprise long thermoplastic fibers and are coated with hydrophilic polymer **binders**. A nonwoven web of poly(ethylene terephthalate) fibers contg. 0.3% carbon black was spray-coated with di-Me silicone, needlepunched, impregnated with an emulsion contg. acrylic acid ester-sodium acrylate copolymer (**glass** transition temp. 3.degree.), squeezed to solids content .apprx.5% (on fiber), and dried 20 min at 150.degree. to give a nonwoven **fabric** with tensile strength 297 and 189 kg/5 cm, resp., in the machine and warp directions and time for sinking in H2O 17 s and time for sinking in seawater 21 s.

L23 ANSWER 4 OF 4 CAPLUS COPYRIGHT 2002 ACS
AN 1995:673985 CAPLUS
DN 123:58215
TI Laminate and molded products from same
IN Aoyama, Kunitoshi; Myazaki, Masaichi
PA Ngk Insulators Ltd, Japan; Nikko Kk
SO Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 07068688	A2	19950314	JP 1993-221895	19930907

AB The title laminate is obtained by laminating a layer based on a compn. contg. wood pulp, natural or **synthetic fiber**, and **binder** with a layer based on a compn. contg. **glass** fiber, **synthetic fiber**, **unwoven** **fabric**, and **binder**. The side with the latter layer is further laminated with a layer based on a compn. contg. wood pulp, natural or **synthetic fiber**, and **binder**. The above laminates are heat and pressure molded in a die to produce products having the desired shape.

=> s melt?(l)fiberglass
L25 5 FILE TEXTILETECH
L26 2 FILE WTEXTILES
L27 3 FILE PIRA
L28 58 FILE CAPLUS

TOTAL FOR ALL FILES
L29 68 MELT?(L) FIBERGLASS

=> d his

```
     (FILE 'HOME' ENTERED AT 14:55:48 ON 27 FEB 2002)

     FILE 'STNGUIDE' ENTERED AT 14:56:20 ON 27 FEB 2002

     FILE 'TEXTILETECH, WTEXTILES, PIRA, CAPLUS' ENTERED AT 15:07:15 ON 27 FEB
     2002
L1          3487 S NON-WOVEN OR UNWOVEN
L2        734698 S FABRIC? OR TEXTILE?
L3         74587 S ( SYNTHETIC FIBER?) OR (SYNTHETIC FIBRE?)
L4         15935 S BINDER? (L) GLASS
                 SET MSTEPS ON
L5             0 FILE TEXTILETECH
L6             7 FILE WTEXTILES
L7             1 FILE PIRA
L8            53 FILE CAPLUS
     TOTAL FOR ALL FILES
L9            61 S L1 (L) L2 (L) L3
L10            0 FILE TEXTILETECH
L11            0 FILE WTEXTILES
L12            0 FILE PIRA
L13            1 FILE CAPLUS
     TOTAL FOR ALL FILES
L14            1 S L9 AND L4
L15            3 FILE TEXTILETECH
L16           12 FILE WTEXTILES
L17           14 FILE PIRA
L18          150 FILE CAPLUS
     TOTAL FOR ALL FILES
L19          179 S L1 AND L2 AND L3
L20            1 FILE TEXTILETECH
L21            1 FILE WTEXTILES
L22            0 FILE PIRA
L23            4 FILE CAPLUS
     TOTAL FOR ALL FILES
L24            6 S L19 AND L4
L25            5 FILE TEXTILETECH
L26            2 FILE WTEXTILES
L27            3 FILE PIRA
L28           58 FILE CAPLUS
     TOTAL FOR ALL FILES
L29           68 S MELT?(L)FIBERGLASS

=> s l19 and l29
L30            0 FILE TEXTILETECH
L31            0 FILE WTEXTILES
L32            0 FILE PIRA
L33            0 FILE CAPLUS

TOTAL FOR ALL FILES
L34            0 L19 AND L29

=> s (thermal? resistan?) or (heat resistan?)
L35          946 FILE TEXTILETECH
L36         3166 FILE WTEXTILES
L37         1627 FILE PIRA
L38       108048 FILE CAPLUS

TOTAL FOR ALL FILES
L39       113787 (THERMAL? RESISTAN?) OR (HEAT RESISTAN?)

=> s l3 and l39
L40           22 FILE TEXTILETECH
```

```
L41         108 FILE WTEXTILES
L42         161 FILE PIRA
L43        3049 FILE CAPLUS

TOTAL FOR ALL FILES
L44        3340 L3 AND L39

=> s l3 (l) l39
L45           8 FILE TEXTILETECH
L46          42 FILE WTEXTILES
L47         143 FILE PIRA
L48        1322 FILE CAPLUS

TOTAL FOR ALL FILES
L49        1515 L3 (L) L39

=> s l1 (l) l2 (l) l49
L50           0 FILE TEXTILETECH
L51           0 FILE WTEXTILES
L52           0 FILE PIRA
L53           1 FILE CAPLUS

TOTAL FOR ALL FILES
L54           1 L1 (L) L2 (L) L49

=> d bib,abs

L54  ANSWER 1 OF 1  CAPLUS  COPYRIGHT 2002 ACS
AN   2001:261205  CAPLUS
DN   134:284305
TI   Laminate, tape, and sheet for oil scattering prevention, and laminate for
     fluid leakage prevention
IN   Tsukada, Masaru
PA   Japan
SO   Jpn. Kokai Tokkyo Koho, 9 pp.
     CODEN: JKXXAF
DT   Patent
LA   Japanese
FAN.CNT 1
     PATENT NO.        KIND  DATE           APPLICATION NO.  DATE
     ---------------   ----  --------       ---------------  --------
PI   JP 2001099419      A2   20010413       JP 1999-321487   19991111
PRAI JP 1999-215190     A    19990729
AB   The laminate for prevention of scattering of high-temp. and high-pressure
     oils such as fuel oils from pipe joints, is made of the following
     substrate (A)-(F) and metal foils of Al, stainless steel, Cu, etc., bonded
     on one side or both sides of the substrate: (A) (non)
     woven fabrics of natural fibers of cotton, hemp, etc.,
     with heat-resistant fibers of synthetic
     fibers (e.g., aramid, polyamide), carbon fibers, inorg. fibers
     (e.g., glass, ceramic), and/or metal fibers (stainless steel, Al, Cu); (B)
     (non)woven fabrics of synthetic
     fibers with heat-resistant fibers of carbon
     fibers, inorg. fibers, and/or metal fibers; (C) (non)
     woven fabrics of .gtoreq.2 heat-
     resistant fibers selected from synthetic fibers
     , carbon fibers, inorg. fibers, and metal fibers; (D) paper; (E) (
     non)woven natural fiber fabrics coated with
     heat-resistant rubbers (e.g., silicone rubber, acrylic
     rubber, Viton) or bonded with heat-resistant films of
     resins (e.g., fluoropolymers, polyimides, polyamides); (F) carbon fiber (
     non)woven fabrics, inorg. fiber (non
     )woven fabrics, metal fiber(non)
```

woven fabrics, A, B, C, or D coated with **heat-resistant** rubbers or bonded with **heat-resistant** resin films. Alternatively, the laminate for oil scattering prevention consists of a foil of Al, stainless steel, Cu, or anticorrosive steel and a sheet or felt of asbestos, ceramic wool, glass wool, or carbon wool fixed on one side of the foil. The tape or the sheet is made of an Al, stainless steel, or Cu foil only. The laminate for leakage prevention of fluid (e.g., oil, water, chems., vapor, gas) uses a substrate film of synthetic resins (e.g., fluoropolymers, polyimides, polyamides) capable of self-shrinking at 80-200.degree., wherein one side or both sides of the film are laminated with synthetic resin films capable of melting at 80-120.degree. or coated with self-curable adhesives of silicone, acrylic, fluorine-type, etc.

```
=> s circuit board?
L55         80 FILE TEXTILETECH
L56         62 FILE WTEXTILES
L57        578 FILE PIRA
L58      29468 FILE CAPLUS

TOTAL FOR ALL FILES
L59      30188 CIRCUIT BOARD?

=> s l19 and l59
L60          0 FILE TEXTILETECH
L61          0 FILE WTEXTILES
L62          0 FILE PIRA
L63          1 FILE CAPLUS

TOTAL FOR ALL FILES
L64          1 L19 AND L59

=> d bib,abs

L64  ANSWER 1 OF 1  CAPLUS  COPYRIGHT 2002 ACS
AN   1994:471600  CAPLUS
DN   121:71600
TI   Manufacture of low expansion multilayer boards for printed circuits
IN   Ikeguchi, Nobuyuki
PA   Mitsubishi Gas Chemical Co, Japan
SO   Jpn. Kokai Tokkyo Koho, 3 pp.
     CODEN: JKXXAF
DT   Patent
LA   Japanese
FAN.CNT 1
     PATENT NO.       KIND  DATE          APPLICATION NO.  DATE
     ---------------  ----  --------      ---------------  --------
PI   JP 05335440       A2   19931217      JP 1992-138880   19920529
AB   The title process comprises formation of an inner printed wiring layer on
     a Cu-laminated total arom. polyamide fiber unwoven base
     .ltoreq.10-5 K-1 in coeff. of thermal expansion, sequential lamination of
     a prepreg for adhesion, and a Cu foil or a single Cu plate laminate
     thereon, and heating-pressing thereof.  The prepreg may be a
     textile from A-, C-, D-, E-, S-, SII-, or T-glass fibers.

=> d ind

L64  ANSWER 1 OF 1  CAPLUS  COPYRIGHT 2002 ACS
IC   ICM  H01L023-12
     ICS  H01L023-14; H05K001-03; H05K003-46
CC   76-2 (Electric Phenomena)
```

Section cross-reference(s): 38

ST printed **circuit board** polyamide fiber laminate

IT Glass fibers, uses
RL: USES (Uses)
(low expansion printed **circuit boards** with prepregs from)

IT Polyamide fibers, uses
Synthetic fibers, polymeric
RL: USES (Uses)
(diaminodiphenyl ether-phenylenediamine-terephthalic acid, low expansion printed **circuit boards** with prepregs from)

IT Polyethers, uses
RL: USES (Uses)
(polyamide-, fiber, low expansion printed **circuit boards** with prepregs from)

IT Electric circuits
(printed, boards, low expansion, from arom. polyamide fibers)

IT 25068-38-6, Epikote 1001 154955-98-3, 2,2-Bis(4-cyanatophenyl)propane-bis(4-maleiimidophenyl)methane copolymer
RL: USES (Uses)
(low expansion printed **circuit boards** from prepregs impregnated with)

IT 24938-64-5 25035-37-4 66559-37-3
RL: USES (Uses)
(low expansion printed **circuit boards** with prepregs from)

=> log y

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	82.77	82.92

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)	SINCE FILE ENTRY	TOTAL SESSION
CA SUBSCRIBER PRICE	-4.34	-4.34